

Description

The TS5A3167 is a single-pole single-throw (SPST) analog switch that is designed to operate from 1.65 V to 5.5 V. The device offers a low ON-state resistance. The device has excellent total harmonic distortion (THD) performance and consumes very low power. These features make this device suitable for portable audio applications.

Applications

- Cell Phones
- PDAs
- Portable Instrumentation
- Audio and Video Signal Routing
- Low-Voltage Data-Acquisition Systems
- Communication Circuits
- Modems
- Hard Drives
- Computer Peripherals
- Wireless Terminals and Peripherals
- Microphone Switching Notebook Docking



FUNCTION TABLE

IN	NC TO COM, COM TO NC
L	ON
Н	OFF

Features

- Isolation in the Powered-Off Mode, V₊ = 0
- Low ON-State Resistance (0.9 Ω)
- Control Inputs Are 5.5-V Tolerant
- Low Charge Injection
- Low Total Harmonic Distortion (THD)
- 1.65-V to 5.5-V Single-Supply Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22

 2000-V Human-Body Model
 - (A114-B, Class II)
 - 1000-V Charged-Device Model (C101)

Summary of Characteristics

 $V_{+} = 5 V, T_{A} = 25^{\circ}C$

Configuration	Single Pole Single Throw (SPST)
Number of channels	1
ON-state resistance (r _{on})	0.9 Ω
ON-state resistance flatness (ron(flat))	0.15 Ω
Turn-on/turn-off time (tON/tOFF)	7.5 ns/12 ns
Charge injection (Q _C)	1 pC
Bandwidth (BW)	200 MHz
OFF isolation (OISO)	–64 dB at 1 MHz
Total harmonic distortion (THD)	0.005%
Leakage current (ICOM(OFF))	±20 nA
Power-supply current (I+)	0.5 μΑ
Package option	5-pin DSBGA, SOT-23, or SC-70



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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ORDERING INFORMATION

TRUMENTS www.ti.com

TA	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING ⁽²⁾
	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YEP		TS5A3167YEPR	PREVIEW
-40°C to 85°C	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)	Tape and reel	TS5A3167YZPR	PACKAGE PREVIEW
	SOT (SOT-23) – DBV	Tape and reel	TS5A3167DBVR	JAT
	SOT (SC-70) – DCK	Tape and reel	TS5A3167DCKR	JG

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.
 (2) DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site.

YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).

Absolute Minimum and Maximum Ratings⁽¹⁾⁽²⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V+	Supply voltage range ⁽³⁾		-0.5	6.5	V
V _{NC} V _{COM}	Analog voltage range(3)(4)(5)		-0.5	V ₊ + 0.5	V
١ĸ	Analog port diode current	V _{NC} , V _{COM} < 0	-50		mA
INC	On-state switch current		-200	200	
ICOM	On-state peak switch current(6)	V_{NC} , $V_{COM} = 0$ to V_+	-400	400	mA
VI	Digital input voltage range(3)(4)		-0.5	6.5	V
Iк	Digital input clamp current	VI < 0	-50		mA
I+	Continuous current through V+			100	mA
IGND	Continuous current through GND		-100		mA
		DBV package		206	
θJA	Package thermal impedance(7)	DCK package		252	°C/W
		YEP/YZP package		132	
T _{stg}	Storage temperature range		-65	150	°C

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

(2) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

(3) All voltages are with respect to ground, unless otherwise specified.

(4) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

(5) This value is limited to 5.5 V maximum.

(6) Pulse at 1-ms duration < 10% duty cycle

(7) The package thermal impedance is calculated in accordance with JESD 51-7.

Electrical Characteristics for 5-V Supply(1) $V_{+} = 4.5 V \text{ to } 5.5 V$, $T_{A} = -40^{\circ}\text{C} \text{ to } 85^{\circ}\text{C}$ (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITI	ONS	TA	V+	MIN	TYP	MAX	UNIT
Analog Switch	•			•	•				
Analog signal range	VCOM, VNC					0		V+	V
Peak ON resistance	r i	$0 \le V_{NC} \le V_+,$	Switch ON,	25 °C	4.5 V		0.8	1.1	Ω
Feak ON resistance	^r peak	ICOM = -100 mA,	See Figure 13	Full	4.5 V			1.2	52
ON-state resistance	ron	V _{NC} = 2.5 V, I _{COM} = -100 mA,	Switch ON, See Figure 13	25°C Full	4.5 V		0.7	0.9	Ω
O N <i>A A A A A A A A A A</i>		$0 \le V_{NC} \le V_+,$ $I_{COM} = -100 \text{ mA}$		25°C			0.15	1	
ON-state resistance flatness	ron(flat)	V _{NC} = 1 V, 1.5 V, 2.5 V,	Switch ON, See Figure 13	25°C	4.5 V		0.09	0.15	Ω
		$I_{COM} = -100 \text{ mA}$	Ū	Full				0.15	
		V _{NC} = 1 V, V _{COM} = 4.5 V,		25°C		-20	4	20	
NC	INC(OFF)	or V _{NC} = 4.5 V, V _{COM} = 1 V	Switch OFF,	Full	5.5 V	-20		20	nA
OFF leakage current		$V_{NC} = 0$ to 5.5 V. See Figure 14		25°C	0.14	-5	0.4	5	
	INC(PWROFF)	V _{COM} = 5.5 V to 0		Full	0 V	-15		15	μA
		$V_{COM} = 1 V, V_{NC} = 4.5 V,$		25°C	551	-20	4	20	
СОМ	ICOM(OFF)	$V_{COM} = 4.5 \text{ V}, V_{NC} = 1 \text{ V}$	Switch OFF,	Full	5.5 V	-100		100	nA
OFF leakage current	1	$V_{COM} = 5.5 V \text{ to } 0,$	See Figure 14	25°C		-5	0.4	5	
	COM(PWROFF)	V _{NC} = 0 to 5.5 V		Full	0 V	–15		15	μA
NC		$V_{NC} = 1 V, V_{COM} = Open,$	Switch ON,	25°C	5 5 V	-2	0.3	2	- 4
ON leakage current	INC(ON)	$V_{\rm NC} = 4.5 \text{ V}, V_{\rm COM} = \text{Open},$	See Figure 15	Full	5.5 V	-20		20	nA
СОМ		$V_{COM} = 1 V, V_{NC} = Open,$	Switch ON,	25°C		-2	0.3	2	
ON leakage current	ICOM(ON)	or $V_{COM} = 4.5 \text{ V}, V_{NC} = \text{Open},$	See Figure 15	Full	5.5 V	-20		20	nA
Digital Control Input	(IN)				1				
Input logic high	VIH			Full		2.4		5.5	V
Input logic low	VIL			Full		0		0.8	V
Input leakage current	lu e lu	V _I = 5.5 V or 0		25°C	5.5 V	-2	0.3	2	nA
input leakage cuffent	liH, liΓ			Full	5.5 V	-20		20	ПА



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Electrical Characteristics for 5-V Supply⁽¹⁾ (continued) $V_{+} = 4.5 V \text{ to } 5.5 V$, $T_{A} = -40^{\circ}\text{C} \text{ to } 85^{\circ}\text{C}$ (unless otherwise noted)

PARAMETER	SYMBOL	TEST CO	NDITIONS	Τ _A	V+	MIN	TYP	MAX	UNIT
Dynamic		•							
Turn-on time	4	$V_{COM} = V_+,$	CL = 35 pF,	25°C	5 V	2.5	4.5	7	
rum-on ume	^t ON	R _L = 50 Ω,	See Figure 17	Full	4.5 V to 5.5 V	1.5		7.5	ns
Turn-off time	torr	$V_{COM} = V_+,$	C _L = 35 pF,	25°C	5 V	6	9	11.5	ns
	tOFF	R _L = 50 Ω,	See Figure 17	Full	4.5 V to 5.5 V	4		12.5	115
Charge injection	QC	V _{GEN} = 0, R _{GEN} = 0,	C _L = 1 nF, See Figure 20	25°C	5 V		1		рС
NC OFF capacitance	C _{NC(OFF)}	$V_{NC} = V_+ \text{ or GND},$ Switch OFF,	See Figure 16	25°C	5 V		19		pF
COM OFF capacitance	C _{COM(OFF)}	$V_{COM} = V_+ \text{ or GND},$ Switch OFF,	See Figure 16	25°C	5 V		18		pF
NC ON capacitance	C _{NC(ON)}	$V_{NC} = V_+ \text{ or GND},$ Switch ON,	See Figure 16	25°C	5 V		35.5		pF
COM ON capacitance	C _{COM(ON)}	$V_{COM} = V_+ \text{ or GND},$ Switch ON,	See Figure 16	25°C	5 V		35.5		pF
Digital input capacitance	Cl	$V_{I} = V_{+}$ or GND,	See Figure 16	25°C	5 V		2		pF
Bandwidth	BW	$R_L = 50 \Omega$, Switch ON,	See Figure 18	25°C	5 V		200		MHz
OFF isolation	O _{ISO}	R _L = 50 Ω, f = 1 MHz,	Switch OFF, See Figure 19	25°C	5 V		-64		dB
Total harmonic distortion	THD	R _L = 600 Ω, C _L = 50 pF,	f = 20 Hz to 20 kHz, See Figure 21	25°C	5 V		0.005		%
Supply	1				1				
Positive supply			0 k k 0 k 0	25°C			0.01	0.1	
current	I+	$V_I = V_+ \text{ or GND},$	Switch ON or OFF	Full	5.5 V			0.5	μA



Electrical Characteristics for 3.3-V Supply(1) $V_{+} = 3 V \text{ to } 3.6 V$, $T_{A} = -40^{\circ}\text{C} \text{ to } 85^{\circ}\text{C}$ (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		TA	V+	MIN	TYP	MAX	UNIT
Analog Switch	•				•				
Analog signal range	VCOM, VNC					0		V+	V
Peak ON resistance	^r peak	$0 \le V_{NC} \le V_+,$ $I_{COM} = -100 \text{ mA},$	Switch ON, See Figure 13	25 °C Full	3 V		1.1	1.5 1.7	Ω
ON-state resistance	r _{on}	V _{NC} = 2 V, I _{COM} = -100 mA,	Switch ON, See Figure 13	25°C Full	3 V		1	1.4 1.5	Ω
ON-state resistance		$0 \le V_{NC} \le V_+,$ I _{COM} = -100 mA	Switch ON,	25°C			0.2		
flatness	^r on(flat)	$V_{NC} = 2 V, 0.8 V,$ $I_{COM} = -100 mA$	See Figure 13	25°C Full	3 V		0.09	0.15 0.15	Ω
		V _{NC} = 1 V, V _{COM} = 3 V,		25°C		-2	0.5	2	
NC	INC(OFF)	or $V_{NC} = 3 V, V_{COM} = 1 V$	Switch OFF,	Full	3.6 V	-20		20	nA
OFF leakage current		V _{NC} = 0 to 3.6 V,	See Figure 14	25°C	0 V	1	0.1	1	μA
	INC(PWROFF)	V _{COM} = 3.6 V to 0		Full	0.0	-5		5	
		$V_{COM} = 1 V, V_{NC} = 3 V,$		25°C	3.6 V	-2	0.5	20	nA
COM	ICOM(OFF)	$V_{COM} = 3 V, V_{NC} = 1 V$	Switch OFF,	Full		-20		20	1
OFF leakage current		$V_{COM} = 3.6 V \text{ to } 0,$	See Figure 14	25°C	οv	-1	0.1	1	μA
	COM(PWROFF)	V _{NC} = 0 to 3.6 V		Full	0 V	-5		5	μΑ
NC	hieren	$V_{NC} = 1 V, V_{COM} = Open,$	Switch ON,	25°C	261/	-2	0.2	2	~ ^
ON leakage current	INC(ON)	$V_{NC} = 3 V, V_{COM} = Open,$	See Figure 15	Full	3.6 V	-20		20	nA
СОМ		$V_{COM} = 1 V, V_{NC} = Open,$	Switch ON,	25°C	0.01/	-2	0.2	2	
ON leakage current	ICOM(ON)	or V _{COM} = 3 V, V _{NC} = Open,	See Figure 15	Full	3.6 V	-20		20	nA
Digital Control Input	(IN)			•					
Input logic high	VIH			Full		2		5.5	V
Input logic low	VIL			Full		0		0.8	V
Input leakage current	1 _{1H} , 1 _{IL}	VI = 5.5 V or 0		25°C	3.6 V	-2	0.3	2	nA
,		1		Full		-20		20	



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Electrical Characteristics for 3.3-V Supply⁽¹⁾ (continued) $V_{+} = 3 V \text{ to } 3.6 V, T_{A} = -40^{\circ}\text{C} \text{ to } 85^{\circ}\text{C} \text{ (unless otherwise noted)}$

PARAMETER	SYMBOL	TEST CO	NDITIONS	TA	V+	MIN	TYP	MAX	UNIT
Dynamic									
Turn-on time	tou	$V_{COM} = V_+,$	C _L = 35 pF,	25°C	3.3 V	2	5	10	ns
	ton	R _L = 50 Ω,	See Figure 17	Full	3 V to 3.6 V	1.5		11	115
Turn-off time	^t OFF	$V_{COM} = V_+,$	C _L = 35 pF,	25°C	3.3 V	6.5	9	12	ns
	UFF	R _L = 50 Ω,	See Figure 17	Full	3 V to 3.6 V	4		13	113
Charge injection	QC	V _{GEN} = 0, R _{GEN} = 0,	C _L = 1 nF, See Figure 20	25°C	3.3 V		1		рС
NC OFF capacitance	C _{NC(OFF)}	V _{NC} = V ₊ or GND, Switch OFF,	See Figure 16	25°C	3.3 V		19		pF
COM OFF capacitance	CCOM(OFF)	$V_{COM} = V_+ \text{ or GND},$ Switch OFF,	See Figure 16	25°C	3.3 V		18		pF
NC ON capacitance	C _{NC(ON)}	V _{NC} = V ₊ or GND, Switch ON,	See Figure 16	25°C	3.3 V		36		pF
COM ON capacitance	C _{COM(ON)}	$V_{COM} = V_+ \text{ or GND},$ Switch ON,	See Figure 16	25°C	3.3 V		36		pF
Digital input capacitance	Cl	$V_{I} = V_{+} \text{ or GND},$	See Figure 16	25°C	3.3 V		2		pF
Bandwidth	BW	$R_L = 50 \Omega$, Switch ON,	See Figure 18	25°C	3.3 V		200		MHz
OFF isolation	O _{ISO}	R _L = 50 Ω, f = 1 MHz,	Switch OFF, See Figure 19	25°C	3.3 V		-64		dB
Total harmonic distortion	THD	R _L = 600 Ω, C _L = 50 pF,	f = 20 Hz to 20 kHz, See Figure 21	25°C	3.3 V		0.01		%
Supply					·				
Positive supply				25°C	2.01/		0.01	0.1	
current	I+	$V_I = V_+ \text{ or GND},$	Switch ON or OFF	Full	3.6 V			0.25	μA



Electrical Characteristics for 2.5-V Supply(1) $V_{+} = 2.3 V \text{ to } 2.7 V$, $T_{A} = -40^{\circ}\text{C} \text{ to } 85^{\circ}\text{C}$ (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		TA	V+	MIN	TYP	MAX	UNIT
Analog Switch	•			•					
Analog signal range	VCOM, VNC					0		V+	V
Peak ON resistance	r _{e e e} le	$0 \le V_{NC} \le V_+,$	Switch ON,	25 °C	2.3 V		1.4	2.2	Ω
Teak ON Tesistance	rpeak	$I_{COM} = -8 \text{ mA},$	See Figure 13	Full	2.5 V			2.4	22
ON-state resistance	ron	V _{NC} = 1.8 V,	Switch ON,	25°C	2.3 V		1.2	1.8	Ω
	ion	$I_{COM} = -8 \text{ mA},$	See Figure 13	Full	2.0 V			2	22
ON-state resistance		$0 \le V_{NC} \le V_+,$ $I_{COM} = -8 \text{ mA}$	Switch ON.	25°C			0.5		-
flatness	^r on(flat)	V _{NC} = 0.8 V, 1.8 V,	See Figure 13	25°C	2.3 V		0.2	0.5	Ω
		$I_{COM} = -8 \text{ mA}$		Full				0.5	
		$V_{\rm NC} = 0.5 \text{ V}, V_{\rm COM} = 2.3 \text{ V},$		25°C		-2	0.5	2	
NC	INC(OFF)	or V _{NC} = 2.3 V, V _{COM} = 0.5 V	Switch OFF,	Full	2.7 V	-20		20	nA
OFF leakage current	h	$V_{NC} = 0$ to 2.7 V,		25°C	οV	-1	0.1	1	μA
	INC(PWROFF)	$V_{COM} = 2.7 V \text{ to } 0$		Full	0 0	-5		5	μι
	1	$V_{COM} = 0.5 V, V_{NC} = 2.3 V,$		25°C	2.7 V	-2	0.5	2	nA
COM	ICOM(OFF)	$V_{COM} = 2.3 \text{ V}, V_{NC} = 0.5 \text{ V}$	Switch OFF,	Full 2.7 V	2.7 V	-20		20	
OFF leakage current		$V_{COM} = 2.7 V \text{ to } 0,$	See Figure 14	25°C	0 V	-1	0.1	1	μA
	COM(PWROFF)	V _{NC} = 0 to 2.7 V		Full	0 V	-5		5	μА
NC		$V_{NC} = 0.5 V, V_{COM} = Open,$	Switch ON,	25°C	071	-2	0.1	2	
ON leakage current	INC(ON)	$V_{\rm NC} = 2.3 \text{ V}, V_{\rm COM} = \text{Open},$	See Figure 15	Full	2.7 V	-20		20	nA
СОМ		$V_{COM} = 0.5 V, V_{NC} = Open,$	Switch ON,	25°C		-2	0.1	2	
ON leakage current	ICOM(ON)	or $V_{COM} = 2.3 \text{ V}, V_{NC} = \text{Open},$	See Figure 15	Full	2.7 V	-20		20	nA
Digital Control Input	(IN)			•					
Input logic high	VIH			Full		1.8		5.5	V
Input logic low	VIL			Full		0		0.6	V
Input leakage	lu e lu			25°C	2.7 V	-2	0.3	2	n 1
current	IIH, IIL	V _I = 5.5 V or 0		Full	2.1 V	-20		20	nA

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Electrical Characteristics for 2.5-V Supply⁽¹⁾ (continued) $V_{+} = 2.3 V \text{ to } 2.7 V$, $T_{A} = -40^{\circ}\text{C} \text{ to } 85^{\circ}\text{C}$ (unless otherwise noted)

PARAMETER	SYMBOL	TEST CO	NDITIONS	TA	V+	MIN	TYP	MAX	UNIT
Dynamic									
Turn-on time		$V_{COM} = V_+,$	C _L = 35 pF,	25°C	2.5 V	3	7	10	
rum-on ume	tON	$R_{L} = 50 \Omega$,	See Figure 17	Full	2.3 V to 2.7 V	2.5		1.5	ns
Turn-off time	torr	$V_{COM} = V_+,$	C _L = 35 pF,	25°C	2.5 V	6.5	9.5	13	ns
	tOFF	R _L = 50 Ω,	See Figure 17	Full	2.3 V to 2.7 V	5		15	115
Charge injection	QC	V _{GEN} = 0, R _{GEN} = 0,	C _L = 1 nF, See Figure 20	25°C	2.5 V		1		рС
NC OFF capacitance	C _{NC(OFF)}	V _{NC} = V ₊ or GND, Switch OFF,	See Figure 16	25°C	2.5 V		19		pF
COM OFF capacitance	CCOM(OFF)	$V_{COM} = V_+ \text{ or GND},$ Switch OFF,	See Figure 16	25°C	2.5 V		18		pF
NC ON capacitance	C _{NC(ON)}	$V_{NC} = V_+ \text{ or GND},$ Switch ON,	See Figure 16	25°C	2.5 V		36.5		pF
COM ON capacitance	C _{COM(ON)}	$V_{COM} = V_+ \text{ or GND},$ Switch ON,	See Figure 16	25°C	2.5 V		36.5		pF
Digital input capacitance	Cl	$V_{I} = V_{+}$ or GND,	See Figure 16	25°C	2.5 V		2		pF
Bandwidth	BW	R _L = 50 Ω, Switch ON,	See Figure 18	25°C	2.5 V		200		MHz
OFF isolation	O _{ISO}	R _L = 50 Ω, f = 1 MHz,	Switch OFF, See Figure 19	25°C	2.5 V		-64		dB
Total harmonic distortion	THD	$R_L = 600 \Omega$, $C_L = 50 pF$,	f = 20 Hz to 20 kHz, See Figure 21	25°C	2.5 V		0.02		%
Supply					1				
Positive supply				25°C	0.7.1/		0.01	0.1	
current	I+	$V_{I} = V_{+}$ or GND,	Switch ON or OFF	Full	2.7 V			0.15	μA



Electrical Characteristics for 1.8-V Supply(1) $V_{+} = 1.65 \text{ V to } 1.95 \text{ V}, T_{A} = -40^{\circ}\text{C} \text{ to } 85^{\circ}\text{C} \text{ (unless otherwise noted)}$

PARAMETER	SYMBOL	TEST CONDITIC	ONS	TA	V+	MIN	TYP	MAX	UNIT
Analog Switch					•				
Analog signal range	V _{COM} , V _{NC}					0		V+	V
Peak ON resistance	re e e la	$0 \le V_{NC} \le V_+,$	Switch ON,	25 °C	1.65 V		3.7	25	Ω
Feak ON resistance	^r peak	$I_{COM} = -2 \text{ mA},$	See Figure 13	Full	1.05 V			30	52
ON-state resistance	ron	V _{NC} = 1.5 V,	Switch ON,	25°C	1.65 V		1.5	3.4	Ω
	.011	$I_{COM} = -2 \text{ mA},$	See Figure 13	Full	1.00 V			3.5	
ON-state resistance		$0 \le V_{NC} \le V_+,$ $I_{COM} = -2 \text{ mA}$	Switch ON,	25°C	()=) (1.5		0
flatness	ron(flat)	V _{NC} = 0.6 V, 1.5 V,	See Figure 13	25°C	1.65 V		2	6	Ω
		$I_{COM} = -2 \text{ mA}$		Full				6	
		$V_{\rm NC} = 0.3 \text{ V}, V_{\rm COM} = 1.65 \text{ V},$		25°C	4.05.14	-2	0.5	2	
NC	INC(OFF)	or $V_{\rm NC} = 1.65 \text{ V}, V_{\rm COM} = 0.3 \text{ V}$	Switch OFF,	Full	1.95 V	-20		20	nA
OFF leakage current		V _{NC} = 0 to 1.95 V,	See Figure 14		οv	-1	0.1	1	μA
	INC(PWROFF)	V _{COM} = 1.95 V to 0		Full	0.0	-5		5	μΑ
		$V_{COM} = 0.3 \text{ V}, V_{NC} = 1.65 \text{ V},$ or		25°C	1.95 V	-2	0.5	2	nA
COM	ICOM(OFF)	$V_{COM} = 1.65 \text{ V}, V_{NC} = 0.3 \text{ V}$	Switch OFF,	Full	1.00 V	-20		20	117
OFF leakage current		V _{COM} = 1.95 V to 0,	See Figure 14	25°C	οv	-1	0.1	1	μA
	COM(PWROFF)	V _{NC} = 0 to 1.95 V		Full	0.0	-5		5	μΛ
NC	hieron	$V_{NC} = 0.3 V$, $V_{COM} = Open$,	Switch ON,	25°C	1.95 V	-2	0.1	2	nA
ON leakage current	INC(ON)	$V_{NC} = 1.65 V, V_{COM} = Open,$	See Figure 15	Full	1.85 V	-20		20	ΠA
СОМ		$V_{COM} = 0.3 V, V_{NC} = Open,$	Switch ON,	25°C	4.05.1/	-2	0.1	2	
ON leakage current	ICOM(ON)	or $V_{COM} = 1.65 \text{ V}, V_{NC} = \text{Open},$	See Figure 15	Full	1.95 V	-20		20	nA
Digital Control Input	(IN)								
Input logic high	VIH			Full		1.5		5.5	V
Input logic low	VIL			Full		0		0.6	V
Input leakage current	lu i lu	VI = 5.5 V or 0		25°C	1.95 V	-2	0.3	2	nA
input leakage cuitent	IIH, IIL	v] = 0.0 v 0i 0		Full	1.90 V	-20		20	IIA



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Electrical Characteristics for 1.8-V Supply⁽¹⁾ (continued) $V_{+} = 1.65 V \text{ to } 1.95 V$, $T_{A} = -40^{\circ}\text{C}$ to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CO	NDITIONS	TA	V+	MIN	TYP	MAX	UNIT
Dynamic	•	·		•	·				•
Turn-on time		$V_{COM} = V_+,$	C _L = 35 pF,	25°C	1.8 V	5.5	5	19	
rum-on ume	ton	R _L = 50 Ω,	See Figure 17	Full	1.65 V to 1.95 V	5		20	ns
Turn-off time	tOFF	$V_{COM} = V_+,$	C _L = 35 pF,	25°C	1.8 V	7.5	12	17.5	ns
	UFF	R _L = 50 Ω,	See Figure 17	Full	1.65 V to 1.95 V	6		20	115
Charge injection	QC	V _{GEN} = 0, R _{GEN} = 0,	C _L = 1 nF, See Figure 20	25°C	1.8 V		1		рС
NC OFF capacitance	C _{NC(OFF)}	V _{NC} = V ₊ or GND, Switch OFF,	See Figure 16	25°C	1.8 V		19		pF
COM OFF capacitance	C _{COM(OFF)}	$V_{COM} = V_+ \text{ or GND},$ Switch OFF,	See Figure 16	25°C	1.8 V		18		pF
NC ON capacitance	C _{NC(ON)}	$V_{NC} = V_+ \text{ or GND},$ Switch ON,	See Figure 16	25°C	1.8 V		37		pF
COM ON capacitance	C _{COM(ON)}	$V_{COM} = V_+ \text{ or GND},$ Switch ON,	See Figure 16	25°C	1.8 V		37		pF
Digital input capacitance	Cl	$V_{I} = V_{+} \text{ or GND},$	See Figure 16	25°C	1.8 V		2		pF
Bandwidth	BW	$R_L = 50 \Omega$, Switch ON,	See Figure 18	25°C	1.8 V		200		MHz
OFF isolation	O _{ISO}	R _L = 50 Ω, f = 1 MHz,	Switch OFF, See Figure 19	25°C	1.8 V		-64		dB
Total harmonic distortion	THD	R _L = 600 Ω, C _L = 50 pF,	f = 20 Hz to 20 kHz, See Figure 21	25°C	1.8 V		0.05		%
Supply	1	1		1	11				1
Positive supply				25°C	4.05.1/		0.01	0.1	
current	I+	$V_I = V_+ \text{ or GND},$	Switch ON or OFF	Full	1.95 V			0.1	μA

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TYPICAL PERFORMANCE



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TYPICAL PERFORMANCE



PIN DESCRIPTION

PIN NUMBER	NAME	DESCRIPTION
1	NC	Normally closed
2	COM	Common
3	GND	Digital ground
4	IN	Digital control pin to connect COM to NC
5	V+	Power supply

PARAMETER DESCRIPTION

SYMBOL	DESCRIPTION
V _{COM}	Voltage at COM
V _{NC}	Voltage at NC
r _{on}	Resistance between COM and NC ports when the channel is ON
^r peak	Peak on-state resistance over a specified voltage range
ron(flat)	Difference between the maximum and minimum value of ron in a channel over the specified range of conditions
INC(OFF)	Leakage current measured at the NC port, with the corresponding channel (NC to COM) in the OFF state under worst-case input and output conditions
INC(PWROFF)	Leakage current measured at the NC port during the power-down condition, $V_+ = 0$
ICOM(OFF)	Leakage current measured at the COM port, with the corresponding channel (COM to NC) in the OFF state under worst-case input and output conditions
ICOM(PWROFF)	Leakage current measured at the COM port during the power-down condition, $V_{+} = 0$
INC(ON)	Leakage current measured at the NC port, with the corresponding channel (NC to COM) in the ON state and the output (COM) open
ICOM(ON)	Leakage current measured at the COM port, with the corresponding channel (COM to NC) in the ON state and the output (NC) open
VIH	Minimum input voltage for logic high for the control input (IN)
VIL	Maximum input voltage for logic low for the control input (IN)
VI	Voltage at the control input (IN)
IIH, IIL	Leakage current measured at the control input (IN)
tON	Turn-on time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM or NC) signal when the switch is turning ON.
tOFF	Turn-off time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM or NC) signal when the switch is turning OFF.
QC	Charge injection is a measurement of unwanted signal coupling from the control (IN) input to the analog (NC or COM) output. This is measured in coulomb (C) and measured by the total charge induced due to switching of the control input. Charge injection, $Q_C = C_L \times \Delta V_{COM}$, C_L is the load capacitance, and ΔV_{COM} is the change in analog output voltage.
C _{NC(OFF)}	Capacitance at the NC port when the corresponding channel (NC to COM) is OFF
C _{COM} (OFF)	Capacitance at the COM port when the corresponding channel (COM to NC) is OFF
C _{NC(ON)}	Capacitance at the NC port when the corresponding channel (NC to COM) is ON
C _{COM} (ON)	Capacitance at the COM port when the corresponding channel (COM to NC) is ON
Cl	Capacitance of control input (IN)
O _{ISO}	OFF isolation of the switch is a measurement of OFF-state switch impedance. This is measured in dB in a specific frequency, with the corresponding channel (NC to COM) in the OFF state.
BW	Bandwidth of the switch. This is the frequency at which the gain of an ON channel is –3 dB below the DC gain.
THD	Total harmonic distortion describes the signal distortion caused by the analog switch. This is defined as the ratio of root mean square (RMS) value of the second, third, and higher harmonic to the absolute magnitude of the fundamental harmonic.
I ₊	Static power-supply current with the control (IN) pin at V ₊ or GND



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PARAMETER MEASUREMENT INFORMATION



Figure 13. ON-State Resistance (ron)



Figure 14. OFF-State Leakage Current (I_{COM(OFF)}, I_{NC(OFF)}, I_{COM(PWROFF)}, I_{NC(PWROFF)})







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(1) All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f < 5 ns, t_f < 5 ns. (2) C_L includes probe and jig capacitance.





Figure 18. Bandwidth (BW)

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Figure 19. OFF Isolation (OISO)



(1) C_L includes probe and jig capacitance.

(2) All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f < 5 ns, t_f < 5 ns.

Figure 20. Charge Injection (Q_C)



(1) CL includes probe and jig capacitance.



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TS5A3167DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS5A3167DBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS5A3167DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS5A3167DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS5A3167DCKRE4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS5A3167DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS5A3167YZPR	ACTIVE	DSBGA	YZP	5	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*A	Il dimensions are nominal												
	Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	TS5A3167DBVR	SOT-23	DBV	5	3000	180.0	9.2	3.23	3.17	1.37	4.0	8.0	Q3
	TS5A3167DCKR	SC70	DCK	5	3000	180.0	9.2	2.24	2.34	1.22	4.0	8.0	Q3



PACKAGE MATERIALS INFORMATION

11-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TS5A3167DBVR	SOT-23	DBV	5	3000	202.0	201.0	28.0
TS5A3167DCKR	SC70	DCK	5	3000	202.0	201.0	28.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.

D. Falls within JEDEC MO-178 Variation AA.



DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-203 variation AA.



YZP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



- B. This drawing is subject to change without notice.
- C. NanoFree™ package configuration.
- D. This package is lead-free. Refer to the 5 YEP package (drawing 4204725) for tin-lead (SnPb).

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